



PRODUCT DATASHEET



N0Q51S30Z



Release Date: 24 May 2020 Version: A1.2



APPLICATIONS:

- Disinfection
- Sterilization
- Bio-Analysis
- Detection

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- Sensor Light
- Fluorescent Spectroscopy
- Counterfeit Detector

3535 1.6t Series



FEATURES:

- Package: UVC SMT Package with Quartz Glass Lens
- Forward Current: 150mA
- Forward Voltage (typ.): 8.0V
- Radiant Power (typ.): 10mW@150mA
- Colour: Ultraviolet (UV)
- Wavelength: 270~280nm
- Viewing angle: 120°
- Materials:

.

- Die: InGaN
- Resin: Quartz Glass (Water Clear)
- Storage Temperature: -40~+100°C
- Grouping parameters:
 - Forward voltage
 - Radiant power
 - Peak Wavelength
- Soldering methods: Reflow soldering
- MSL: Level 3 according to J-STD020
- Packing: 12mm tape with max.500pcs/reel, ø180mm (7")





Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Maximum Forward Current	Імах	150	mA
Power Dissipation	PD	1000	mW
Reverse Voltage	V _R	5	V
Reverse Current @5V	Ir	10	μΑ
Operating Temperature	Torg	-10~+60	°C
Storage Temperature	Тѕтб	-40~+100	°C
Solder Temperature	Tsol	260	°C

Electrical & Optical Characteristics (Ta=25°C)

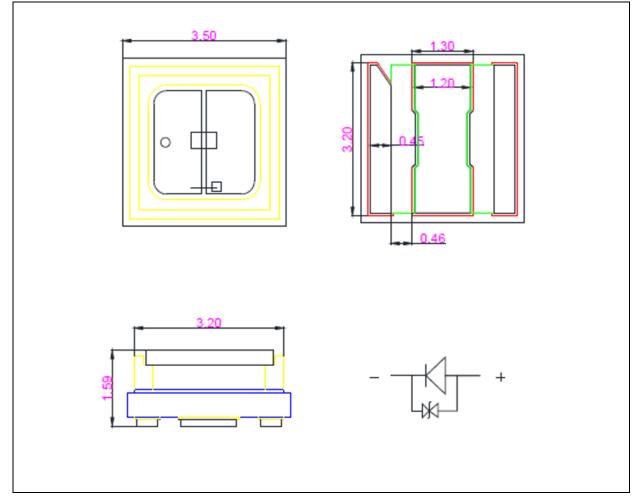
Parameter	Symbol	Values		Unit	Test	
	Symbol	Min.	Тур.	Max.	Onit	Condition
Forward Voltage	VF	7.0	8.0	9.0	V	I⊧=150mA
Radiant Power	Po		10.0		mW	I⊧=150mA
Peak Wavelength	Wp	270	275	280	nm	I⊧=150mA
Spectrum Half Width	Δλ		11	15	nm	l⊧=150mA
Viewing Angle	2 θ 1/2		120		deg	l⊧=150mA

 $1. \qquad \text{Radiant Power (P_0) \pm 10\%, Forward Voltage (V_F) \pm 0.2V, Viewing angle(2\theta_{1/2}) \pm 10^{\circ}, Peak Wavelength (nm) \pm 3nm}$



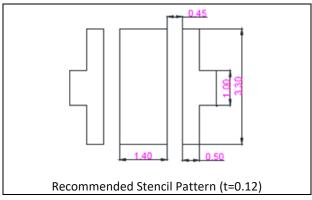


Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ± 0.13 mm, unless otherwise noted.

Recommended Soldering Pad Dimension:



- 1. Dimensions are in millimetre (mm).
- 2. Tolerance ± 0.13 mm with angle tolerance $\pm 0.5^{\circ}$.





Forward Voltage Classifications (I_F = 150mA):

Code	Min.	Max.	Unit
V1	7.0	9.0	V

Radiant Power Classifications (I_F = 150mA):

Code	Min.	Max.	Unit
H1	4	18	mW

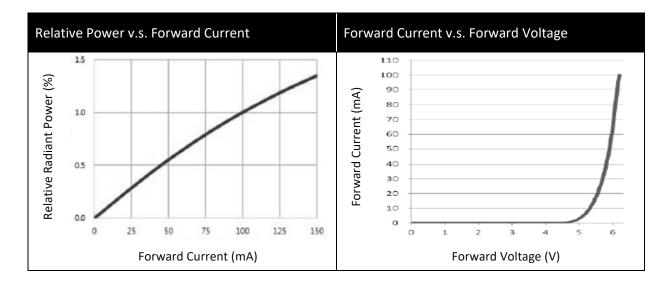
Wavelength Classifications (I_F = 150mA):

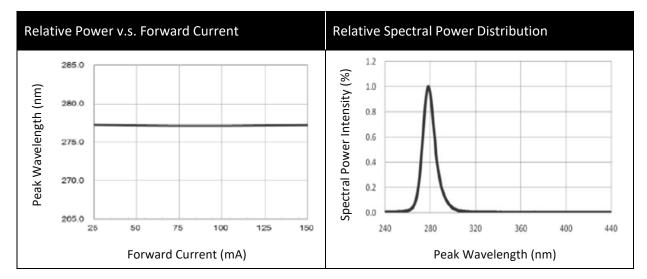
Code	Min.	Max.	Unit
UVC	270	280	nm

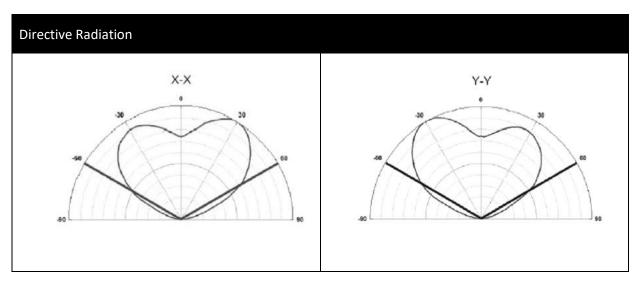




ELECTRO-OPTICAL CHARACTERISTICS:



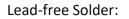


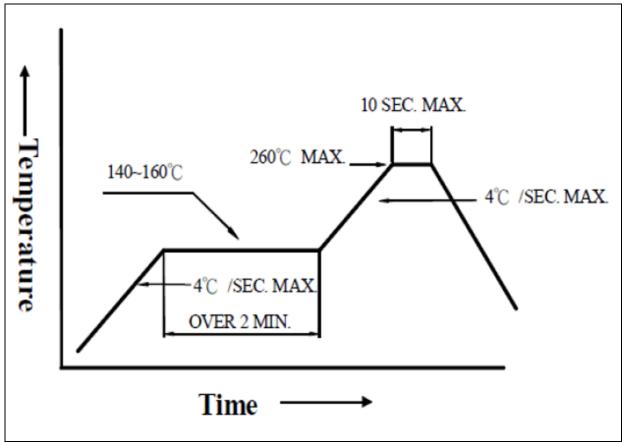






RECOMMENDED SOLDERING PROFILE:





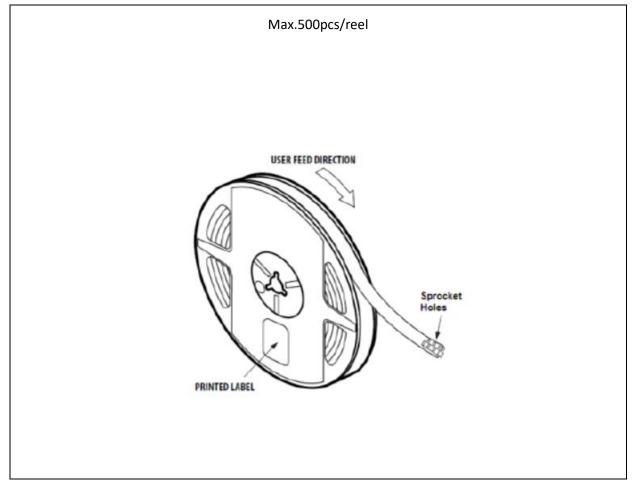
Note:

- 1. Maximum reflow soldering: 1 time.
- 2. Recommended reflow temperature 240°C. Maximum soldering temperature should be limited to 245°C.
- 3. Before, during, and after soldering, should not apply stress on the components and PCB board.





Reel Dimension:







Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent under <10% R.H. and apply baking before use.

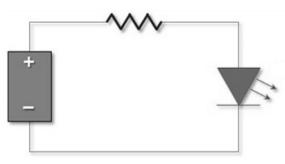
Baking:

It is required to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

• 60±5°C x 48hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.





REVISION RECORD:

Version	Date	Summary of Revision
A1.0	19/04/2020	Datasheet set-up.
A1.1	21/05/2020	Correct part number.
A1.2	24/05/2020	Add product photo.